

ABSTRACT

The present invention provides a photosensitive resin composition which uses a polyimide precursor that has excellent solubility in organic solvents and is capable of reducing the viscosity of a resin composition obtained therefrom. The solution according to the present invention is a photosensitive resin composition which contains: an aromatic amide resin that has, as a main repeating unit, a specific structure having an amide group, a trifluoromethyl group and an aromatic ring; (b) a sensitizer; and (c) a solvent.